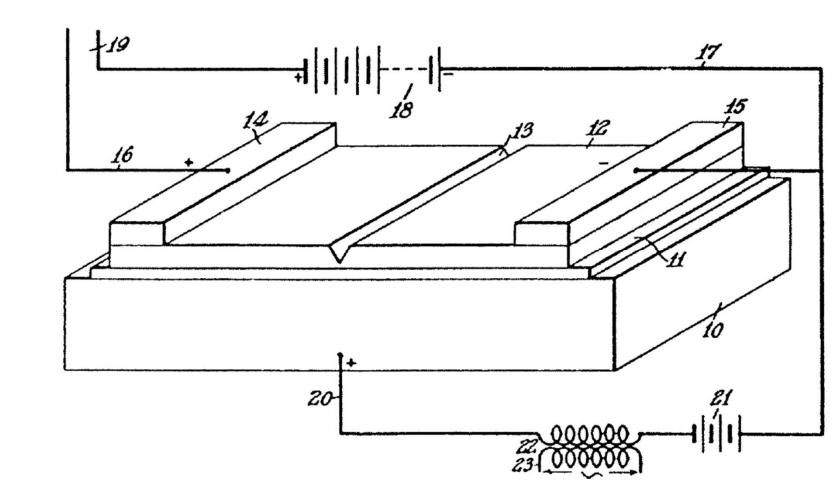
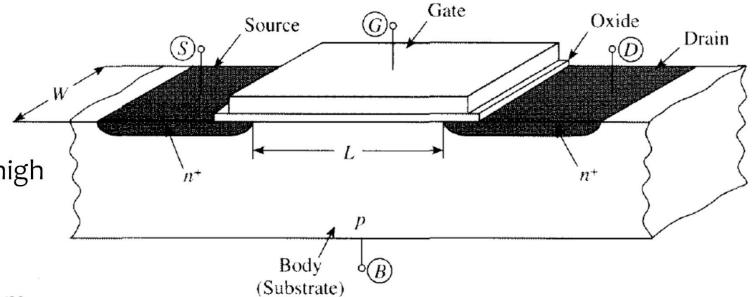
- ■Basic idea 1930, . Lilienfeld
- ■Lab study 1940, Heil
- Development method for growing oxide –1960, Kahng and Atalla



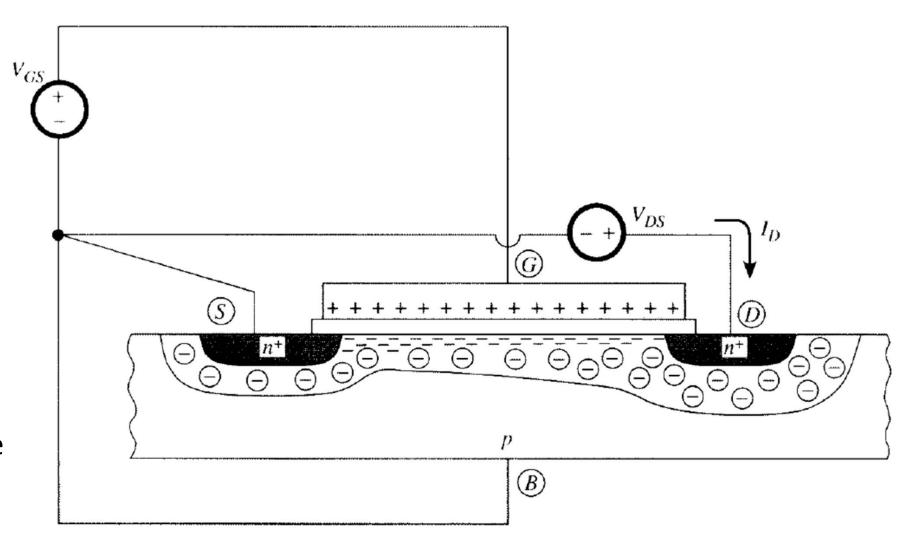
- Simple operation of n-MOS
- ■p-doped Body concentration: 10<sup>16</sup> /cm<sup>3</sup> to 10<sup>18</sup>/cm<sup>3</sup>
- Body or substrate
- Oxide thickness: 1.2 nm (high performance) to 10s nm (high voltage transistor)
- ■Gate: heavily doped n or p type polysilicon (10<sup>20</sup>/cm<sup>3</sup>)
- Source and Drain: heavily doped n type dopant with 10 nm depth in modern technology
- Lateral diffusion: 10 nm in modern technology due to high temp. fabrication steps –ion movement
- Channel: w×L, where L is the channel length.
- ■In digital application L designed so that become minimum



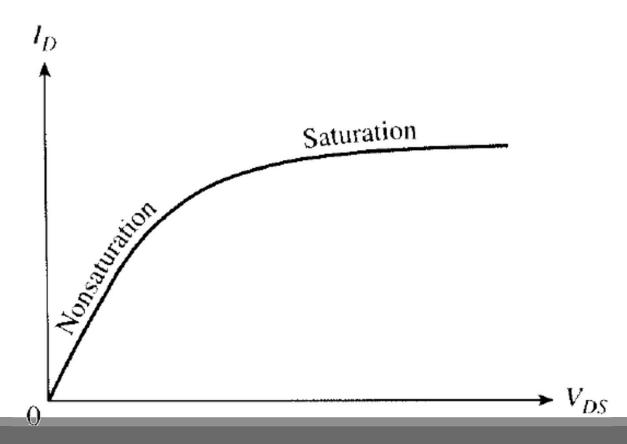
- ■The positive gate potential effect: preparing the channel by attracting the electron to oxide semiconductor interference
- ■The number of electrons in the channel can be varied through the gate potential Channel strength variation.
- Source and Drain bias
  - With same voltage bias: no current
  - with different bias voltage: one with lower voltage act like a source and inject electron to channel and the other one sinks electrons of channel
- ■S, G,D and B acronyms
- MOS, MOSFET, MOST (MOS Transistor), IGFET (insulated-gate field-effect transistor).
- ■Leakage current (1 pA): source and drain biased so that become negative in compare to body voltage. This current increases with temp. (double for each & C)



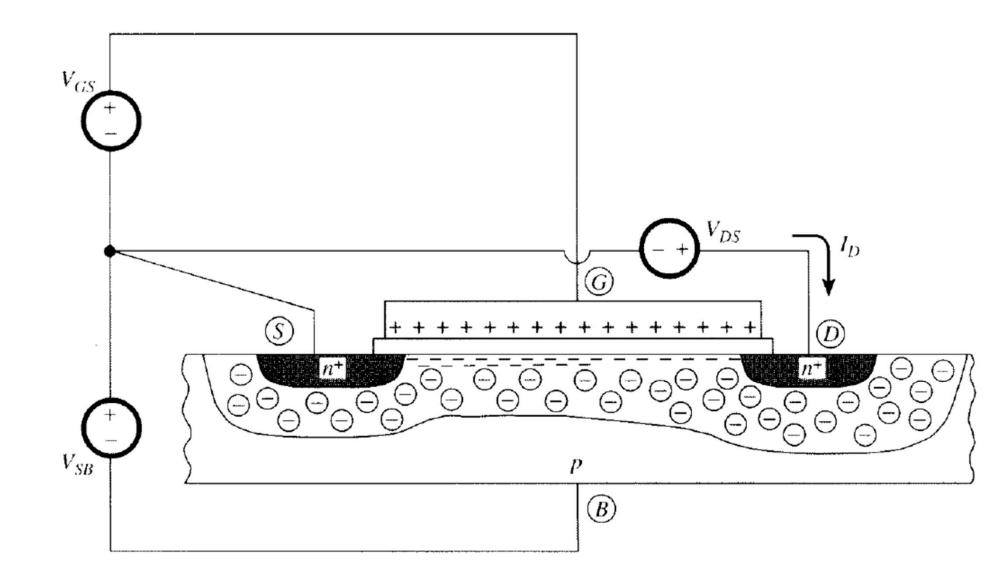
- ■A Qualitative Description of MOS Transistor Operation
- ■Channel formation <u>Inversion</u> layer
  - First holes repel from the surface
  - Second electrons attracted to surface
    - Electrons in body
    - Electrons in source and drain
- Weak, Moderate and Strong inversion
- Source and drain to body junction:
  - Form 2 np junction
  - Reverse bias, why?
  - $V_{DB}>V_{SB}$  → more electrons near the source



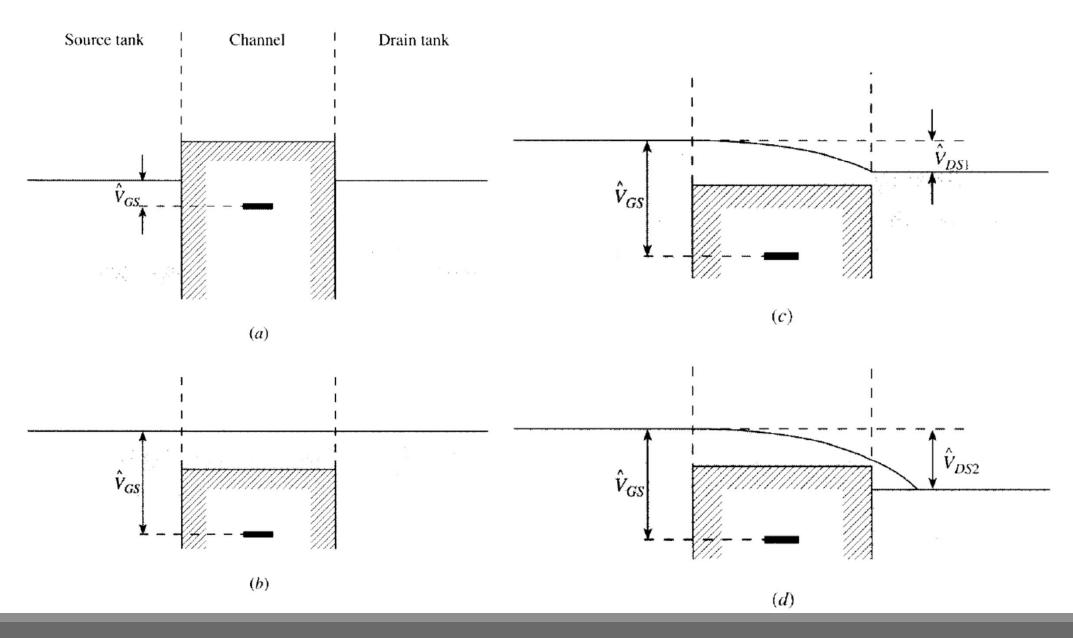
- Drain source voltage: V<sub>DS</sub>
  - Electron movement: As it is positive electrons flow from source to drain!
  - Constant current: Slow movement near source and speed up near drain
- ■Current and V<sub>DS</sub> Dependency
  - Saturation region- Pinch off
  - Nonsaturation region or linear region Resistor



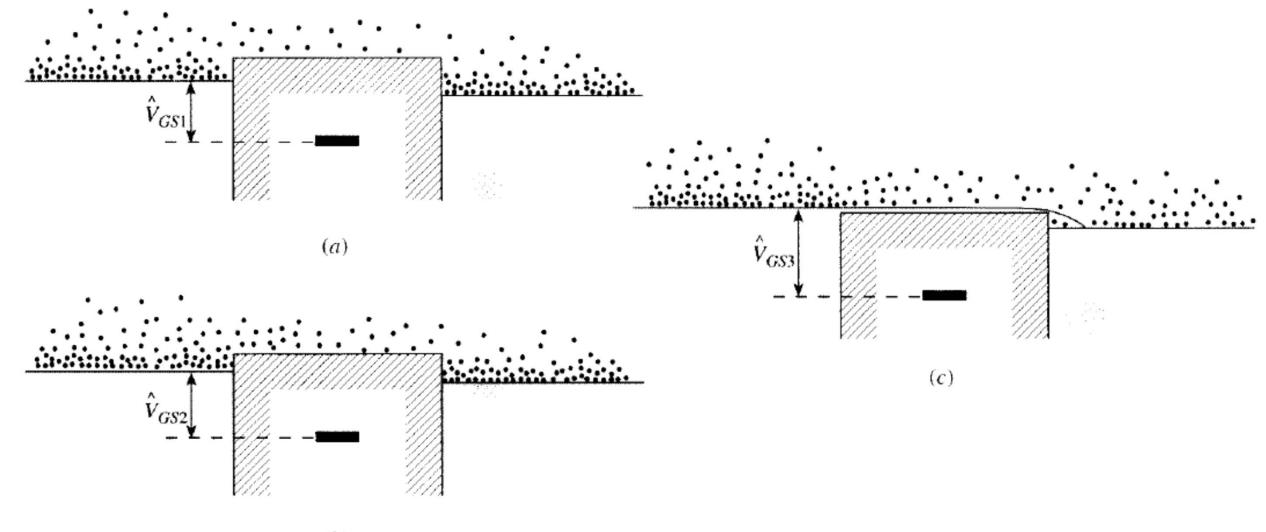
- ■V<sub>SB</sub> effect Body effect
  - Decreasing the current, why?
  - Back gate concept



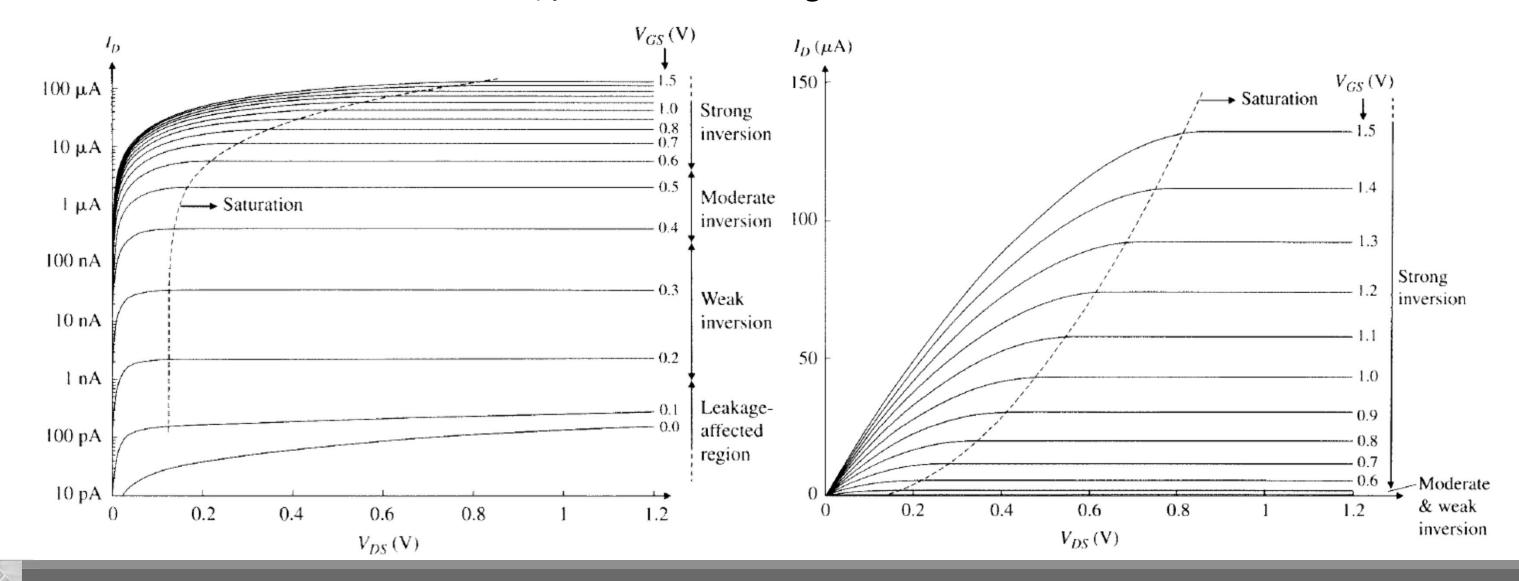
A Fluid Dynamical Analog



Carrier distribution in Weak and Moderate regime



MOS Transistor Characteristics – Typical value for long channel MOS



#### Operation region

- Weak inversion
  - Diffusion mechanism is permanent
  - ∘ I<sub>D</sub> is exponentially related to V<sub>GS</sub>—Like BJT
- Moderate inversion
  - Drift and Diffusion mechanism present
- Strong inversion
  - Drift mechanism is permanent
  - I<sub>D</sub> has quadratic relation to V<sub>GS</sub>

